



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-01-07
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STB10NK60Z-1	TLI7*EZ66H62	A	SHENZHEN B/E	2016-01-07
Amount		UoM	Unit type	ST ECOPACK Grade
1500.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	4.5, 10.2, 10.55	2	THROUGH HOLE	
Comment	I2PAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TLI7*EZ6H62					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	12.748	mg	supplier	die	Silicon (Si)	7440-21-3		12.305	mg	965247	8203
				supplier	metallization	Aluminium (Al)	7429-90-5		0.173	mg	13572	115
				supplier	Passivation	Silicon Nitride	12033-89-5		0.058	mg	4550	39
				supplier	Passivation	Silicon Oxide	7631-86-9		0.092	mg	7217	61
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.006	mg	471	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.084	mg	6590	56
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.030	mg	2353	20
Leadframe	Copper & its alloys	840.769	mg	supplier	alloy	Copper (Cu)	7440-50-8		838.515	mg	997319	559010
				supplier	alloy	Iron (Fe)	7439-89-6		0.386	mg	459	257
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.705	mg	839	470
				supplier	metallization	Nickel (Ni)	7440-02-0		1.156	mg	1375	771
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	8	5
Soft solder	Solder	11.493	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	10.976	mg	955016	7317
				supplier	solder	Silver (Ag)	7440-22-4		0.287	mg	24972	191
				supplier	solder	Tin (Sn)	7440-31-5		0.230	mg	20012	153
Bonding wires	Other inorganic materials	0.433	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.433	mg	999077	289
				supplier	wire	Magnesium (Mg)	7439-95-4		0.000	mg	923	0
Encapsulation	Other Organic Materials	630.652	mg	supplier	mold compound	Silica, vitreous	60676-86-0		548.668	mg	870001	365779
				supplier	mold compound	Epoxy resin	25068-38-6		63.065	mg	100000	42043
				supplier	mold compound	Phenol resin	29690-82-2		15.766	mg	25000	10511
				supplier	mold compound	Carbon Black	1333-86-4		3.153	mg	5000	2102
Connections coating	Solder	3.905	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.905	mg	1000000	2603